### Monday 5 October
- **11th European FIB Users Group Meeting, EFUG workshop**

### Tuesday 6 October
- **Tutorial “MEMS Reliability: Where are we now?”**
- **Tutorial “ESD testing of devices, ICs and systems”**
- **Lunch**
- **Tutorial “Physical Mechanisms and Modeling of the Bias Temperature Instability”**

### Wednesday 7 October
- **Session F: Extreme environments: Power devices reliability**
  - Invited “Reliability challenges of automotive power electronics”
- **Coffee break**
- **Session C1: Electron and Optical Beam Testing (EOBT)**
  - Invited “Laser THz emission microscope as a novel tool for LSI failure analysis”
- **Lunch**
- **Sessions C1 C2 Advanced Techniques for failure analysis and Case studies**
  - Invited “Physical Analysis, Trimming and Editing of Nanoscale IC Function with Backside FIB Processing”
- **Workshop EUFANET**

### Thursday 8 October
- **Session B2: Failure Mechanisms in Si technologies and Nanoelectronics (Low K materials, Cu interconnects, ESD …)**
  - Invited “Do ESD fails in systems correlate with IC ESD robustness?”
- **Coffee break**
- **Session E: Packaging, Passive Components and MEMS**
  - Invited “Reliability, Prognostics and Risk Assessment Modelling for Electronics Packaging”
- **Lunch**
- **Session B1: Failure Mechanisms in Si technologies and Nanoelectronics: NBTI**
  - Invited “Best Paper RCJ”
- **Coffee break**
- **Session B1: Failure Mechanisms in Si technologies and Nanoelectronics: Oxide Reliability**

### Friday 9 October
- **Session D: Failure Mechanisms in Microwave and High Bandgap Devices**
  - Invited “GaN HEMT Reliability”
- **Coffee break**
- **Session D: Failure Mechanisms in Photonic Devices**
  - Invited “Towards Reliable Thin-Film Encapsulation of Organic Electronic Devices”
- **BPA And closing**
- **LOTUS Workshop**